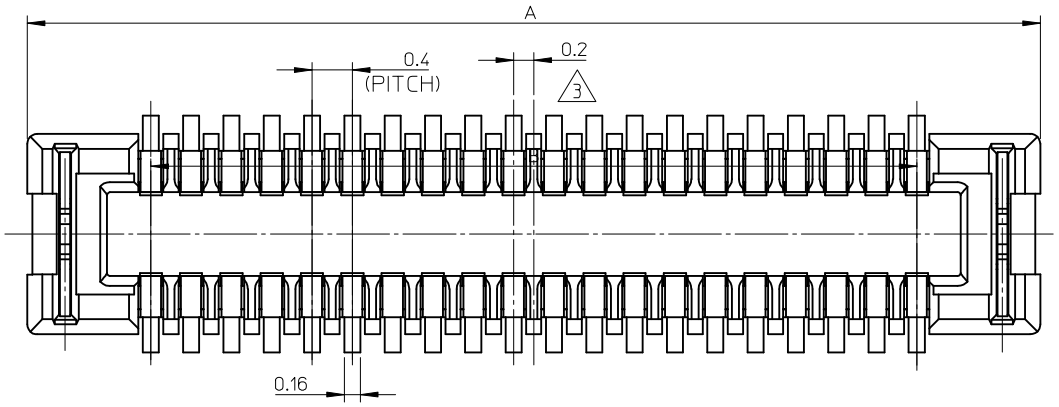
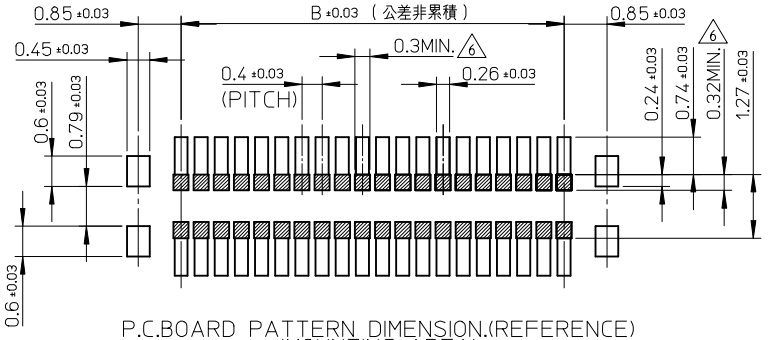
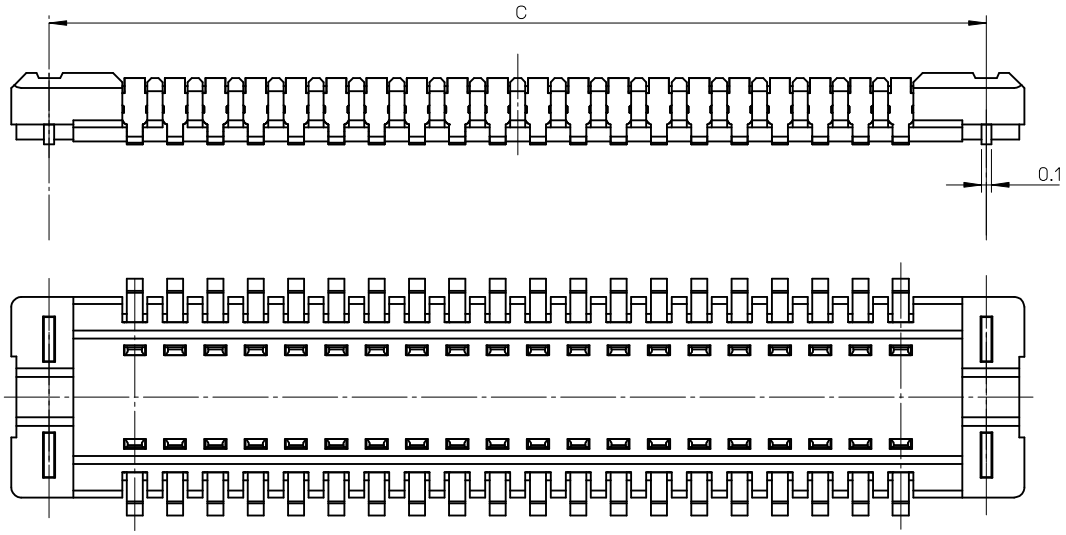
THE DATASHEET OF

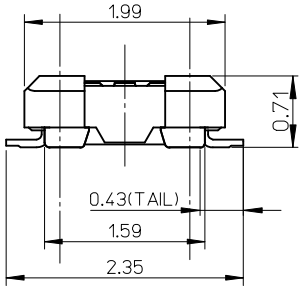
501594-1211





P.C.BOARD PATTERN DIMENSION.(REFERENCE)
(MOUNTING AREA)





C	B	A	EMBOSSED TAPE PACKAGE / ORDER No.	MATERIAL NO.	CIRCUIT
15.3	13.6	16.05	501594-7011	501594-7010	70
12.1	10.4	12.85	501594-5411	501594-5410	54
11.3	9.6	12.05	501594-5011	501594-5010	50
10.1	8.4	10.85	501594-4411	501594-4410	44
9.3	7.6	10.05	501594-4011	501594-4010	40
8.1	6.4	8.85	501594-3411	501594-3410	34
7.3	5.6	8.05	501594-3011	501594-3010	30
6.5	4.8	7.25	501594-2611	501594-2610	26
6.1	4.4	6.85	501594-2411	501594-2410	24
5.7	4.0	6.45	501594-2211	501594-2210	22
5.3	3.6	6.05	501594-2011	501594-2010	20
3.7	2.0	4.45	501594-1211	501594-1210	12
3.3	1.6	4.05	501594-1011	501594-1010	10

REVISED
EC NO: J2008-3370 2008/06/17
DRWN:KSETO 2008/06/17
CH'KD:MSASAO
APPR:MSASAO 2008/06/25
DESCRIPTION
REV E

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: T.ASAKAWA DATE: 2006/07/10
CHECKED BY: M.SASAO DATE: 2006/07/10
APPROVED BY: M.SASAO DATE: 2006/07/10

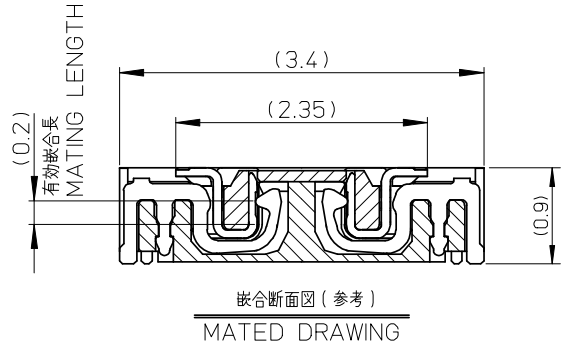
TITLE: 0.4MM PITCH B/B CONN. H=0.9 W=3.4 PLUG ASSY

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-501594-005
SHEET NO.: 1 OF 2

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



嵌合断面図（参考）
MATED DRAWING

注記 NOTES

1.使用材料
MATERIAL

ハウジング：液晶ポリマー（LCP） ガラス充填 UL-94V-0（黒）
HOSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0 (COLOR:BLACK)

ターミナル：りん青銅（t=0.08）
TERMINAL : PHOSHOR BRONZE (t=0.08)

金具 ：りん青銅（t=0.1）
FITTING NAIL : PHOSHOR BRONZE (t=0.1)

2.メッキ仕様
PLATING

ターミナル
TERMINAL

金メッキ 0.1マイクロメートル以上（コンタクト部）
GOLD 0.1 MICROMETER MINIMUM (CONTACT AERA)

金メッキ 0.03マイクロメートル以上（テール部）
GOLD 0.03 MICROMETER MINIMUM (TAIL AERA)

下地メッキ：ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING : NICKEL 1.0 MICROMETER MINIMUM

金具
FITTING NAIL

錫メッキ :1.0マイクロメートル以上
TIN PLATING :1.0 MICROMETER MINIMUM

下地メッキ :ニッケル1.0マイクロメートル以上
UNDER PLATING :NICKEL 1.0 MICROMETER MINIMUM

△3 (全極数/2)=偶数の場合に適用
APPLY FOR (CIRCUIT/2)=EVEN

4.嵌合相手 : 501591-**10シリーズ
WITH MATE : 501591-**10SERIES

5.テール及び金具の平坦度は、0.1以下
TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM

△6 斜線部はパターン書き込み禁止範囲と半田禁止範囲を示す。
ただし、斜線部に同一配線を配置する場合はレジストを施し、この部分に半田は無きこと。
NO PATTERN CIRCUIT AND NO SOLDER ALLOWED IN THE SHADED AREA.
HOWEVER, IF NEEDED TO ADD A TRACE OF THE SAME CIRCUIT, PUT THE SOLDER-RESIST, YET NO SOLDER ALLOWED IN THE AREA.

7.ELV AND RoHS COMPLIANT.

REVISED				DESCRIPTION	REV
EC NO: J2008-3370	DRWN:KSETO	CH'KD:MSASAO	APPR:MSASAO		
2008/06/17	2008/06/17	2008/06/25			

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	T.ASAKAWA	DATE 2006/07/10
CHECKED BY	M.SASAO	DATE 2006/07/10
APPROVED BY	M.SASAO	DATE 2006/07/10

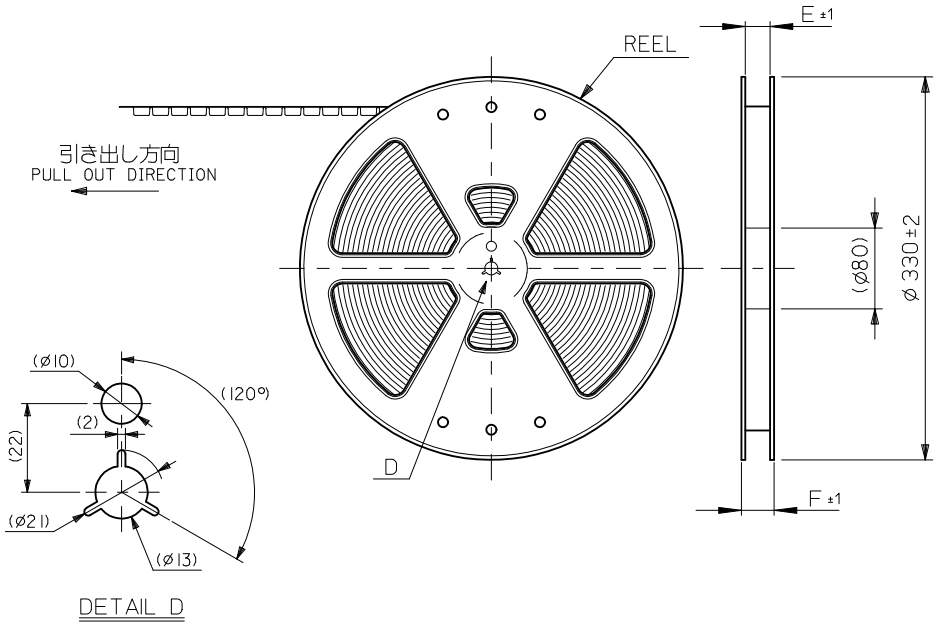
TITLE: 0.4MM PITCH B/B CONN. H=0.9 W=3.4 PLUG ASSY

MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE SHEET 1	SD-501594-005	2 OF 2

SIZE A3

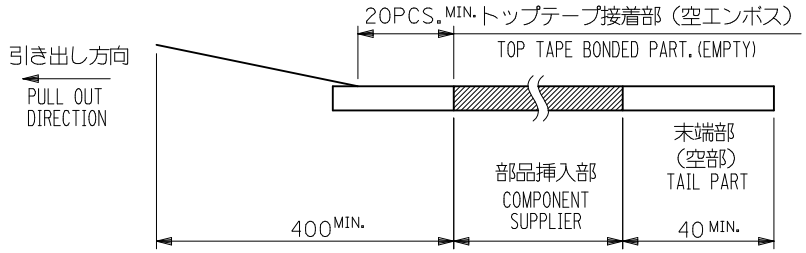
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



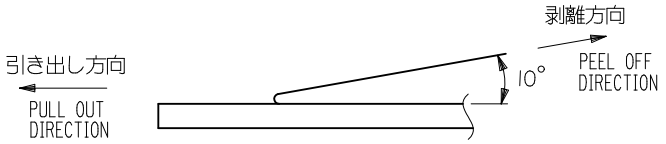
DETAIL D

NOTES

1. 製品詳細寸法については製品単体図面を参照下さい。
   RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2. 梱包数量： 3000 個／リール
   NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：JES-59 参照
   剥離方向は下図参照。
   PEELING OFF STRENGTH OF TOP TAPE : REFER TO JES-59
   PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE.



5. 材料 MATERIAL
   キャリアテープ (CARRIER TAPE)：ポリスチレン （POLYSTYRENE）
   トップテープ (TOPTAPE)： PET ，PE ，PEF
   リール (REEL)： ポリスチレン（ＰＳ） <リサイクル材を含む>
   POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

6. ELV AND RoHS COMPLIANT.

REVISED
EC NO: J2012-0023 2011/07/05
DRWN:KTOYODA 2011/07/06
CH'KD:TASAKAWA 2011/11/30
APPR:MSASAO
DESCRIPTION
REV E

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

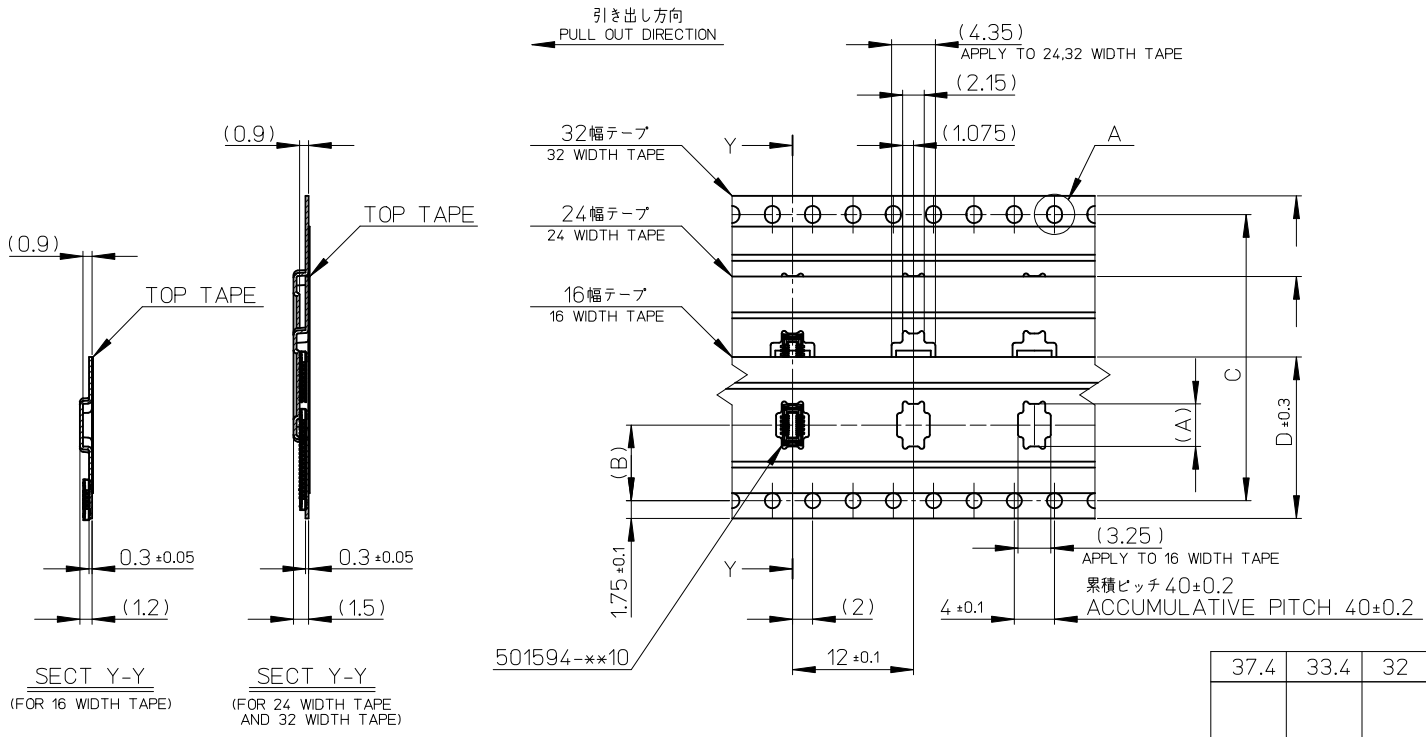
DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	TASAKAWA
DATE	2006/07/10
CHECKED BY	MSASAO
DATE	2006/07/10
APPROVED BY	MSASAO
DATE	2006/07/10
MATERIAL NO.	SEE SHEET 1
DOCUMENT NO.	SD-501594-006
SHEET NO.	1 OF 2
SIZE	A3

501594-**11 MODEL NO.

TITLE: 0.4MM PITCH B/B CONN. PLUG ASSY (HGT=0.9) EMBSTP PKG

MOLEX INCORPORATED

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



F	E	D	C	(B)	(A)	MATERIAL NO.	極数 CKT.
21.4	17.4	16	—	7.5	4.61	501594-1211	12
					4.21	501594-1011	10
29.4	25.4	24	—	11.5	16.21	501594-7011	70
					13.01	501594-5411	54
					12.21	501594-5011	50
					11.01	501594-4411	44
					10.21	501594-4011	40
					9.01	501594-3411	34
					8.21	501594-3011	30
					7.41	501594-2611	26
					7.01	501594-2411	24
					6.61	501594-2211	22
					6.21	501594-2011	20
37.4	33.4	32	28.4	14.2	16.21	501594-7011	70

501594-**11 MODEL NO.

REVISED
E EC NO: J2012-0023 2011/07/06
DRWN:KTOYODA 2011/07/06
CH'KD:TASAKAWA 2011/11/30
APPR:MSASAO
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: TASAKAWA DATE: 2006/07/10
CHECKED BY: MSASAO DATE: 2006/07/10
APPROVED BY: MSASAO DATE: 2006/07/10
MATERIAL NO.: SEE TABLE

TITLE: 0.4MM PITCH B/B CONN. PLUG ASSY (HGT=0.9) EMBSTP PKG

MOLEX INCORPORATED

DOCUMENT NO.: SD-501594-006
SHEET NO.: 2 OF 2

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- View 501594-1211 on WIN SOURCE
- Molex, LLC Information

Optimize Your Supply Chain with WIN SOURCE Solutions

- Global Sourcing Solution
- Obsolete Management
- Cost Control Management
- Shortage Management
- Alternative Solution
- Excess Inventory Management